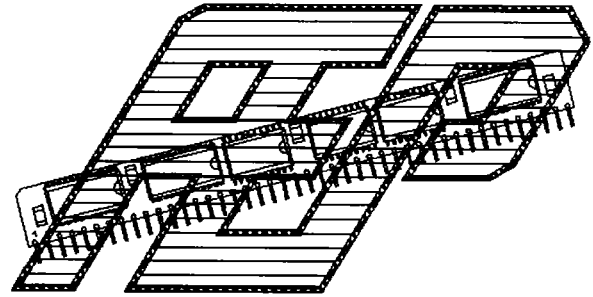


- >> 262,144 x 9 Organization
- >> On board BUFFERS for all address and control lines
- >> Low profile design, 0.5 inch stand-off height.
- >> Double sided to maximize bit density
- >> Completely Static operation
- >> TTL compatible
- >> Uses single +5V power supply



**256 KILO-WORD BY 9 BIT HIGH
 SPEED STATIC RAM MODULE
 WITH ON-BOARD BUFFERS**

DESCRIPTION:

The AEPSS256K9B is a high speed, high density 256 kilo-word by 9 bit static random access memory module with on board buffering of all address and control lines. Physically it consists of an FR4 PC material substrate surface mounted with nine 256K x 1 high speed static RAM ICs, three 244 type buffer ICs, five 0.18 microfarad decoupling capacitors, and 44 press-in I/O pins in a single-inline-package format.

The module can use any of the 256K x 1 SRAMs with SOJ lead packages and standard pin-out made by any of a variety of manufacturers. A wide range of access speeds are available.

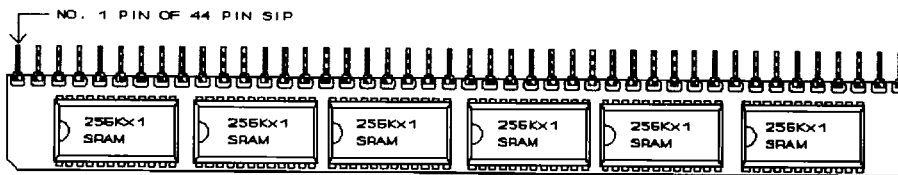
Performance specifications and electrical characteristics are determined by the IC devices used. These items can vary according to the type and manufacturer of the components. The necessary information is obtained from the IC vendors' data sheets, like those attached, or from their data books.

Mechanical dimensions are 0.50 in. high by 4.40 in. long by 0.32 in. wide. The I/O pins are on 0.1 inch center spacing.

A 64K x 9B version is also available. Both versions can be made in a by 8 bit organization on request.

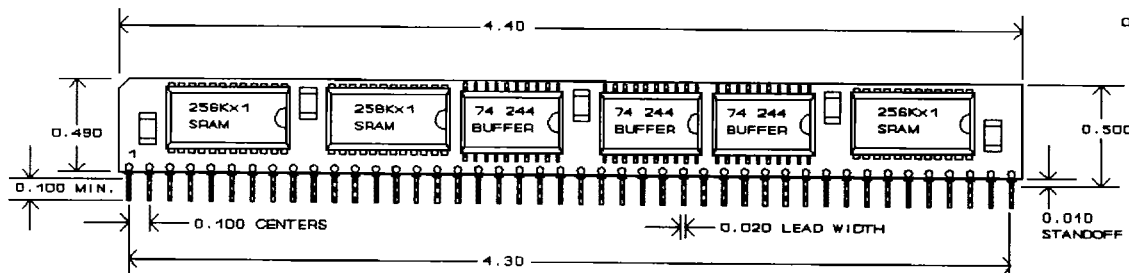
**SPECIFICATION DRAWING
 256K9B SRAM**

DIMENSION IN INCHES, TOLERANCE: +/- 0.010 UNLESS SPECIFIED.



NOTE: 64Kx9B VERSION
 USES 64Kx1 SRAMs

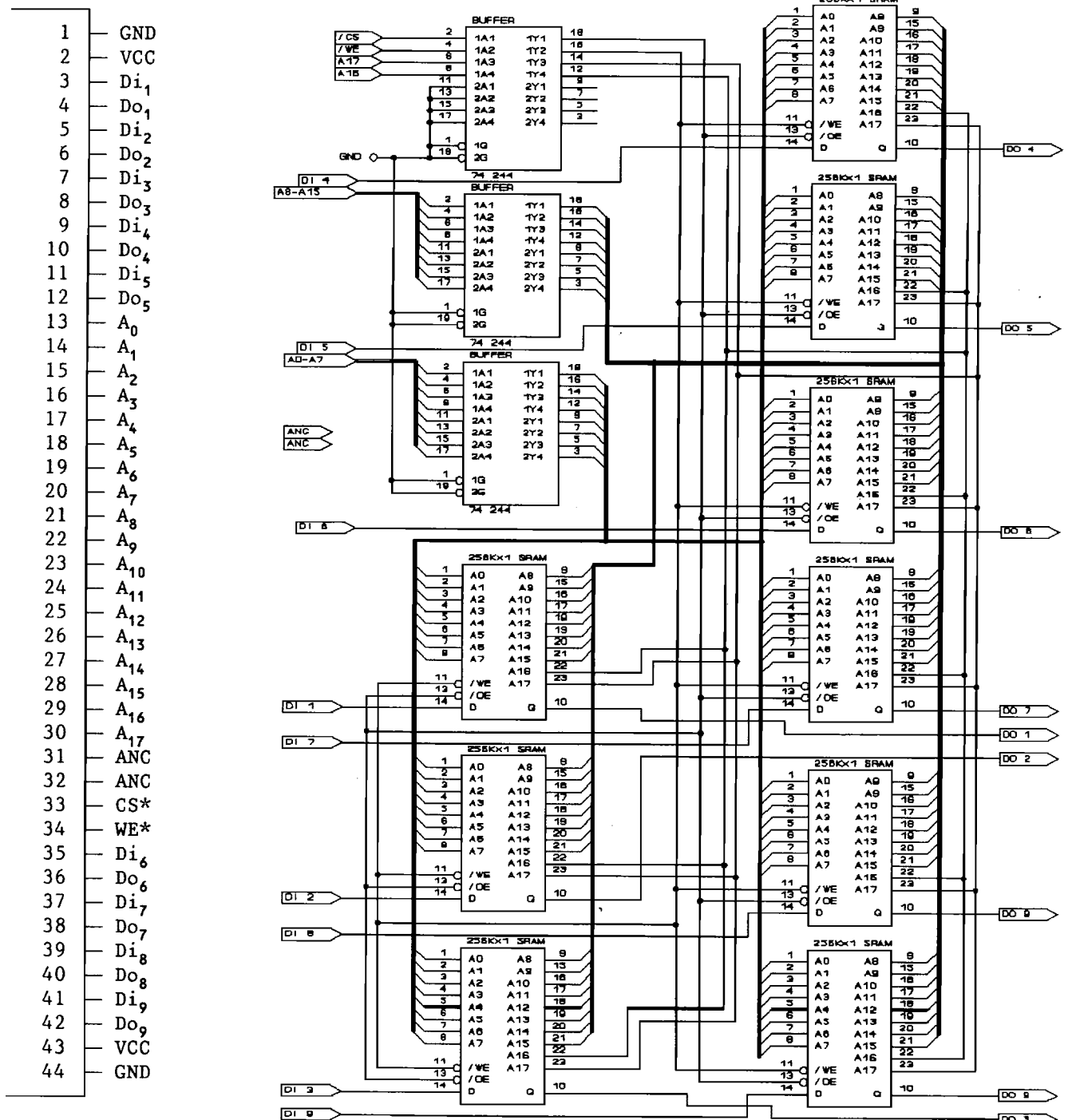
REAR VIEW



BUFFERED HIGH SPEED 256K x 9 STATIC RAM

PIN-OUT CONFIGURATION

FUNCTIONAL DIAGRAM



* ACTIVE WHEN LOW

ANC - reserved for next generation address line.
 NOTES: pins 29 and 30 no connects on 64K x 9B version.

